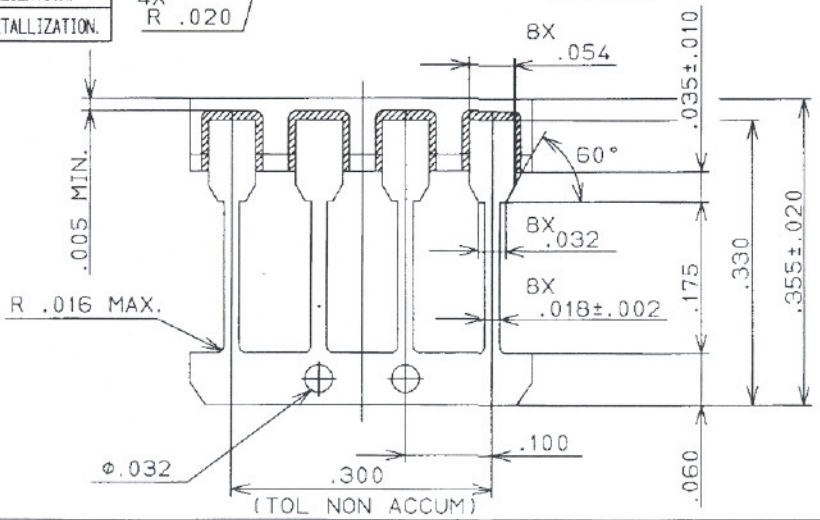


PART No.	NOTCH AREA METALLIZED
01	WITH METALLIZATION.
02	WITHOUT METALLIZATION.

LEAD No.1  
4X  
R .020

4X  
R .035

8X  
.054

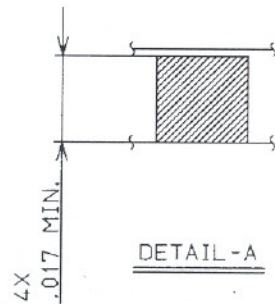
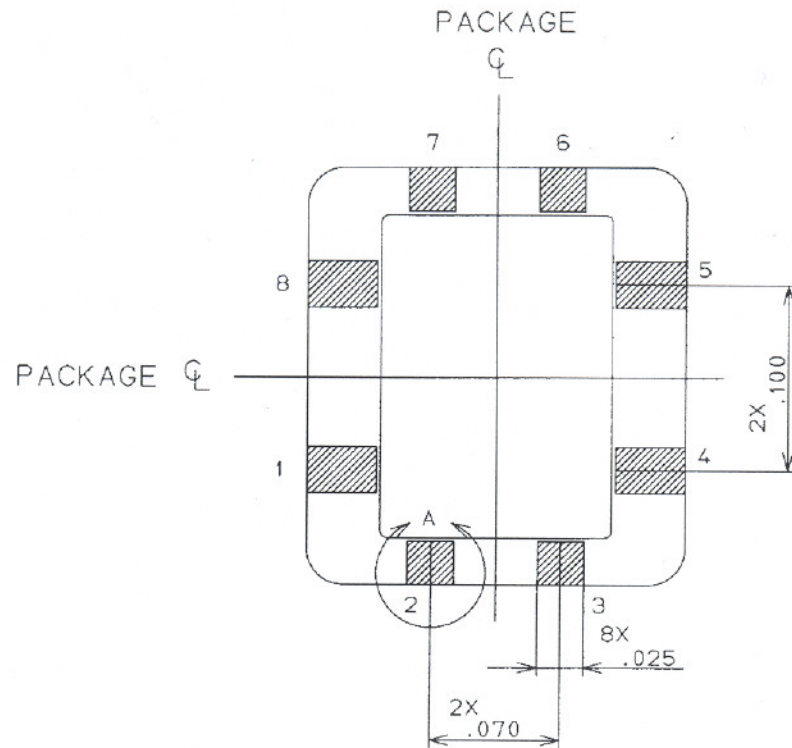


NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE : 0.20 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEAD.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB008P832-2	S=0 D=0		
SB008P832-1	S=0 D=0		
DRAWN	CHECKED	APPROVED	DATE
S.N	T.A		NOV.28.'84
DRAWING NO.			SHEET
KD-S84832-B			1/2

MODIFICATION						NAME	TOLERANCE
						8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED
						SCALE 7/1	±.005
						MATERIAL AS INDICATED	THIRD ANGLE PROJECTION
	ADDED : PART No.02, NOTE 6.7, CHANGED : SHEET No.2	APR.5.'87	Y.H	H.Y/M.SU	H.SA	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN
	REDRAWN (CONVERTED CAD DATA)	APR.4.'85	Y.M	T.C/S.F	T.A		
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	T.A		NOV.28.'84
						SCALE 15 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	REDRAWN	APR.5.'87	Y.H	H.Y/M.S.U	H.SA			DRAWING NO.			SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	KD-S84832-B			2 / 2